

KBU8005~KBU810

Rev.C Feb.-2015

描述 / Descriptions

整流桥，反向电压：50V~1000V，正向电流：8.0A，KBU 封装。
Silicon Bridge Rectifiers, Reverse Voltage:50to1000V,Forward Current:8.0A,KBU package.

特征 / Features

浪涌额定过载电流 155A，塑料材料阻燃等级 UL94-V0。
Surge overload rating -155 amperes peak,Plastic material has UL94-V0.

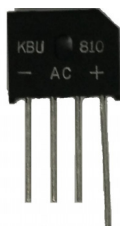
用途 / Applications

一般用途。
General purpose.

内部等效电路图 / Equivalent Circuit

见引脚排列图/ See Pinning.

引脚排列 / Pinning



印章代码 / Marking

See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		KBU8005	KBU801	KBU802	KBU804	KBU806	KBU808	KBU810	
Maximum Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V _{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Output Current at T _C =100°C	I _(AV)	8.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load(JEDEC Method)	I _{FSM}	155							A
Typical Junction Capacitance Per Element (Note1)	C _j	250							pF
Operating Temperature Range	T _j	-55~150							°C
Storage Temperature Range	T _{stg}	-55~150							°C

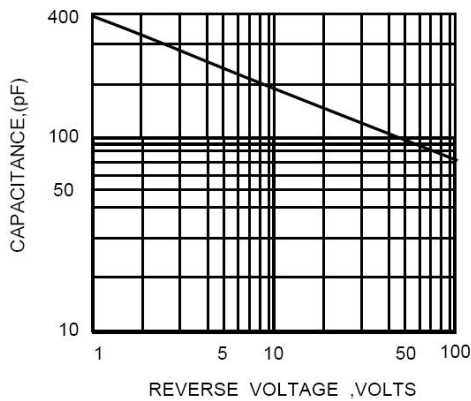
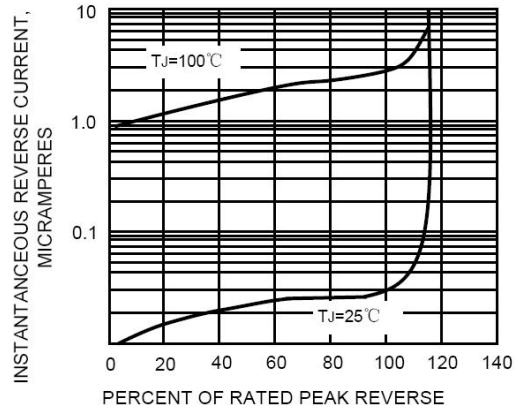
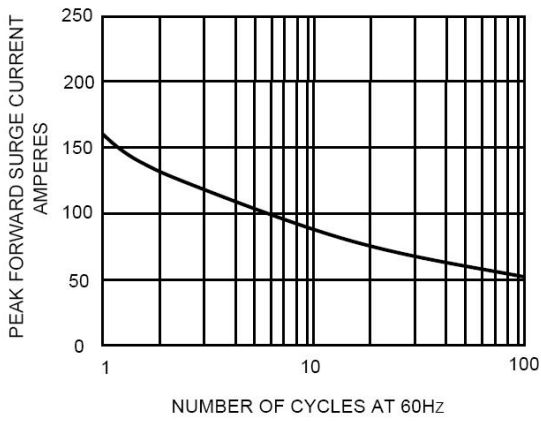
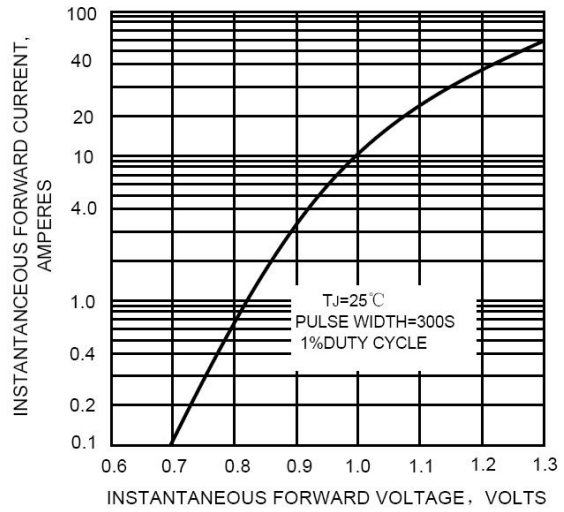
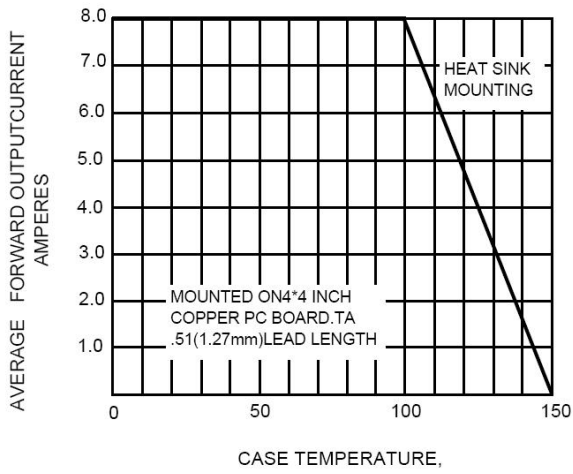
Note:

1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

电性能参数 / Electrical Characteristics(Ta=25°C)

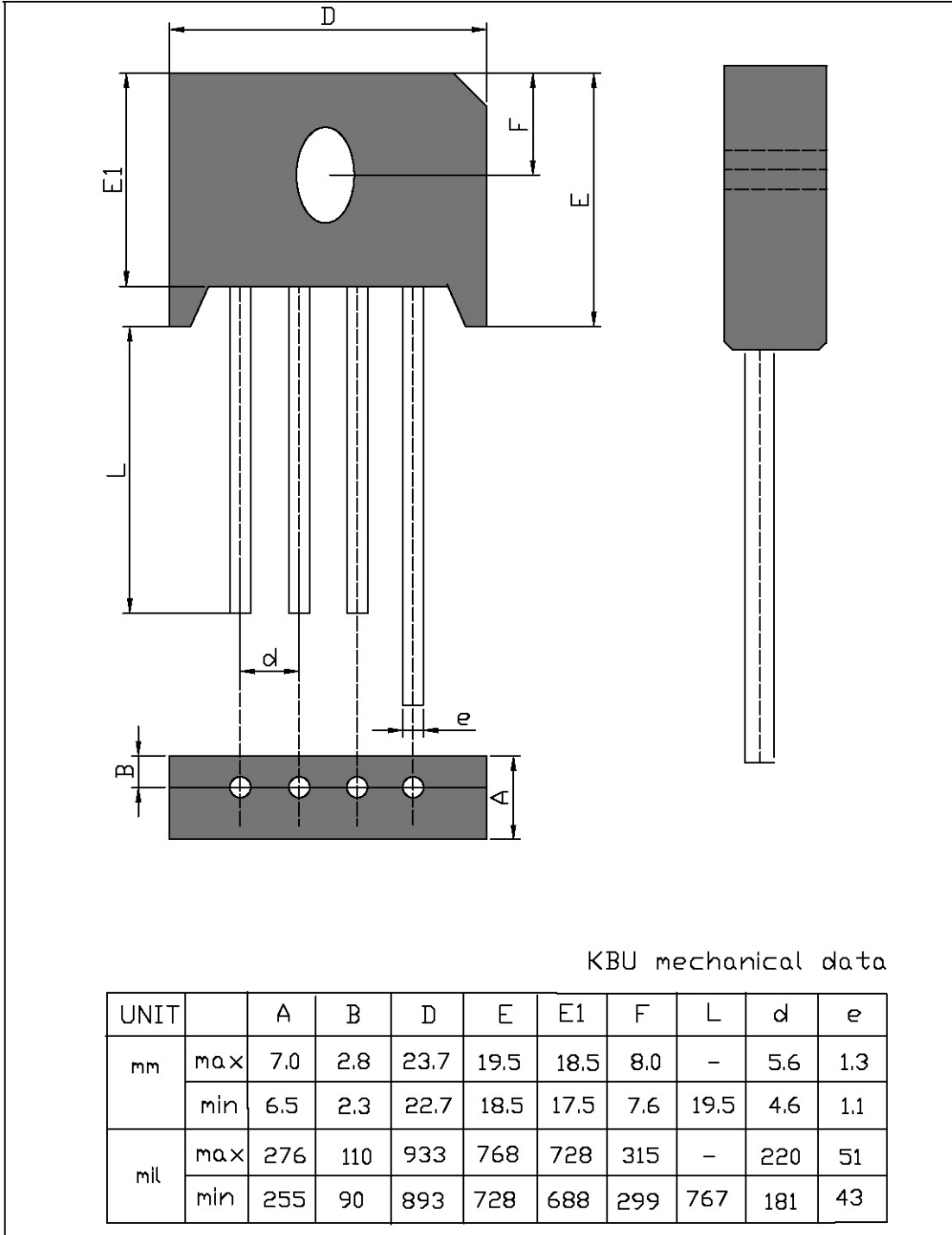
参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Maximum Instantaneous Forward Voltage Drop per Element	V _F	I _F =4.0A	1.0	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I _R	T _J =25°C	10	μA
		T _J =100°C	300	μA

电参数曲线图 / Electrical Characteristic Curve

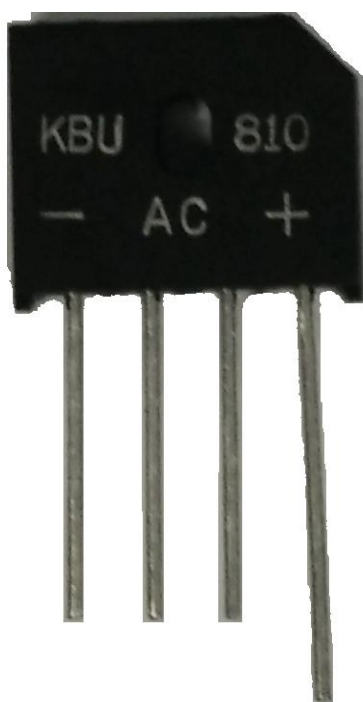


外形尺寸图 / Package Dimensions

KUB



印章说明 / Marking Instructions



说明：

KBU810：产品型号

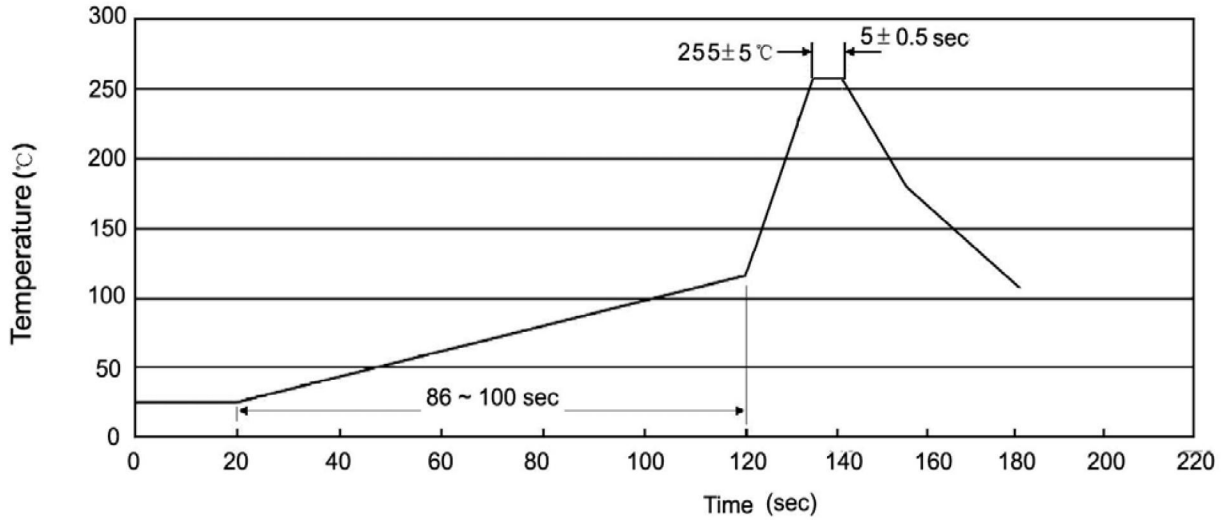
- AC +：引脚功能

Note:

KBU810：Product Type

- AC +：Pin function

波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

盒装包装 / BOXED

Package Type 封装形式	Units 包装数量			Dimension 包装尺寸 (unit: mm ³)		
	Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱		Inner Box 盒	Outer Box 箱
KBU	400	6	2400		230×230×49	490×240×180

使用说明 / Notices